

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-8 (Canceled).

Claim 9 (Currently Amended): A power module comprising:

a first substrate with a power semiconductor device mounted thereon;

a second substrate with a control circuit for controlling said power semiconductor device formed thereon;

a smoothing capacitor electrically connected to said power semiconductor device for smoothing a voltage to be externally supplied to said power semiconductor device; and

a case including a case frame and a case lid, said case having an interior in which said first substrate, said second substrate and said smoothing capacitor are disposed, and said smoothing capacitor is disposed in contact with a side surface of said case frame.

Claims 10-15 (Canceled).

Claim 16 (Currently Amended): ~~The power module according to claim 9, further A~~
power module comprising:

a first substrate with a power semiconductor device mounted thereon;

a second substrate with a control circuit for controlling said power semiconductor device formed thereon;

a smoothing capacitor electrically connected to said power semiconductor device for smoothing a voltage to be externally supplied to said power semiconductor device;

a case including a case frame and a case lid, said case having an interior in which said first substrate, said second substrate and said smoothing capacitor are disposed; and

a heat sink for dissipating heat generated from said first substrate, said first substrate and said case frame being placed on said heat sink,

wherein said smoothing capacitor is disposed on said heat sink.

Claim 17 (Original): The power module according to claim 9,
wherein said smoothing capacitor is a ceramic capacitor.

Claim 18 (New): The power module according to claim 9,
wherein said smoothing capacitor is buried in said case frame.